

# Bill of Materials

TI DESIGNS

TIDA-00388

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	1	C1	0.1uF	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R,	TDK	C1608X7R1H104K		0603	
2	9	C2, C4, C9, C10, C16, C19, C22, C23, C24	47uF	CAP, CERM, 47 µF, 16 V, +/- 15%, X5R, 1206	TDK	C3216X5R1C476M160A B		1206	
3	2	C3, C14	0.01uF	CAP, CERM, 0.01 µF, 50 V, +/- 10%, X8R, 0603	TDK	C1608X8R1H103K		0603	
4	1	C5	22uF	CAP, CERM, 22 µF, 35 V, +/- 20%, X5R, 0805	TDK	C2012X5R1V226M125A C		0805	
5	1	C7	4700pF	CAP, CERM, 4700 pF, 50 V, +/- 10%, X8R, 0603	TDK	C1608X8R1H472K		0603	
6	1	C8	1000pF	CAP, CERM, 1000 pF, 100 V, +/- 5%, X7R,	AVX	06031C102JAT2A		0603	
7	1	C11	330pF	CAP, CERM, 330 pF, 50 V, +/- 1%,	TDK	C1608C0G1H331F080AA		0603	
8	1	C12	0.1uF	CAP, CERM, 0.1 µF, 50 V, +/- 10%,	TDK	C1005X7R1H104K		0402	
9	2	C13, C15	22uF	CAP, CERM, 22uF, 35V, +/-20%, JB, 0805	TDK	C2012JB1V226M125AC		0805	
10	1	C17	0.01uF	CAP, CERM, 0.01uF, 16V, +/-10%, X7R,	MuRata	GRM188R71C103KA01D		0603	
11	1	C18	4.7uF	CAP, CERM, 4.7uF, 10V, +/-10%, X5R, 0603	TDK	CGB3B1X5R1A475K055		0603	
12	1	C20	220uF	CAP, AL, 220 µF, 6.3 V, +/- 20%, 0.015 ohm,	Sanyo	6SVPE220MW		E61	
13	2	C21, C25	3300pF	CAP, CERM, 3300 pF, 50 V, +/- 5%,	TDK	C1608C0G1H332J		0603	
14	1	C26	1000pF	CAP, CERM, 1000 pF, 50 V, +/- 5%,	TDK	C1608C0G1H102J		0603	
15	1	C27	10uF	CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R,	TDK	C2012X5R0J106M		0805	
16	6	J1, J2, J3, J4, JP3, JP4		Header, TH, 100mil, 2x1, Gold plated, 230	Samtec	TSW-102-07-G-S		2x1 Header	
17	1	J7		Header, 100mil, 2x1, Gold, TH	Samtec	TSW-102-07-G-S		2x1 Header	
18	1	JP1		Header, TH, 100mil, 3x1, Gold plated, 230	Samtec	TSW-103-07-G-S		3x1 Header	
19	1	JP2		Header, 100mil, 3x1, Gold, TH	Samtec	TSW-103-07-G-S		3x1 Header	
20	1	L1	1.5uH	Inductor, Shielded, Composite, 1.5 µH, 7.12	Coilcraft	XAL4020-152MEB		4x2.1x4mm	
21	1	R1	3.57k	RES, 3.57k ohm, 0.1%, 0.1W, 0603	Susumu Co Ltd	RG1608P-3571-B-T5		0603	
22	1	R2	4.02k	RES, 4.02 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW06034K02FKEA		0603	
23	1	R3	392k	RES, 392 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW0603392KFKEA		0603	
24	1	R4	27.4k	RES, 27.4 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW060327K4FKEA		0603	
25	1	R5	10.0k	RES, 10.0 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW060310K0FKEA		0603	
26	1	R6	22.1k	RES, 22.1 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW060322K1FKEA		0603	
27	1	R7	10k	RES, 10k ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW060310K0JNEA		0603	
28	1	R8	10k	RES, 10k ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW040210K0JNED		0402	
29	2	R9, R12	3.92	RES, 3.92, 1%, 0.1 W, 0603	Vishay-Dale	CRCW06033R92FKEA		0603	
30	1	R10	160k	RES, 160 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW0603160KFKEA		0603	
31	1	R11	0	RES, 0, 5%, 0.063 W, 0402	Vishay-Dale	CRCW04020000Z0ED		0402	
32	1	TP1	Red	Test Point, Miniature, Red, TH	Keystone	5000		Red Miniature	
33	2	TP2, TP5	Black	Test Point, Miniature, Black, TH	Keystone	5001		Black Miniature	
34	2	TP3, TP4	White	Test Point, Miniature, White, TH	Keystone	5002		White Miniature	
35	1	U1	TPS54122RHL	IC, Low Noise LDO, 3-A Power Supply with	TI	TPS54122RHL		QFN-24	
36	1	C6	10pF	CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0,	TDK	C1608C0G1H100D		0603	
37	0	J5, J6		Connector, End launch SMA, 50 ohm, SMT	Emerson Network Pow	142-0701-851		SMA End	

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